



Material Content Data Sheet



Sales Product Name		BBY 55-02V H6327		Issued		25. September 2017		
MA#		MA000787824						
Package		PG-SC79-2-1		Weight*		1.68 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		24	
	noble metal	gold	7440-57-5	0.004	0.23		2331	
	inorganic material	silicon	7440-21-3	0.033	1.99	2.22	19910	22265
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		92	
	non noble metal	titanium	7440-32-6	0.001	0.05		459	
	non noble metal	chromium	7440-47-3	0.002	0.14		1377	
	non noble metal	copper	7440-50-8	0.767	45.73	45.93	457314	459242
wire	non noble metal	copper	7440-50-8	0.007	0.41	0.41	4052	4052
encapsulation	organic material	carbon black	1333-86-4	0.007	0.43		4293	
	plastics	epoxy resin	-	0.122	7.30		72980	
	inorganic material	silicondioxide	60676-86-0	0.591	35.20	42.93	352022	429295
leadfinish	non noble metal	tin	7440-31-5	0.055	3.25	3.25	32529	32529
plating	noble metal	silver	7440-22-4	0.088	5.26	5.26	52617	52617
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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